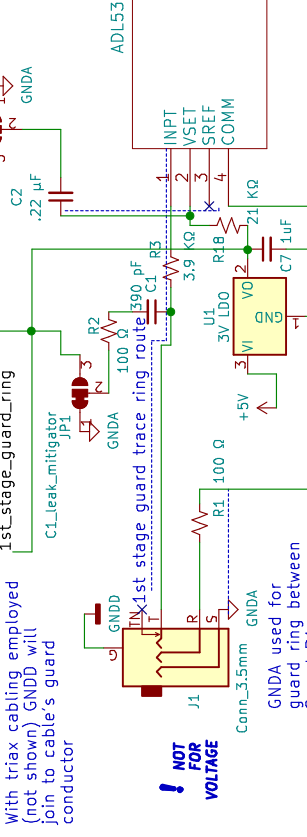


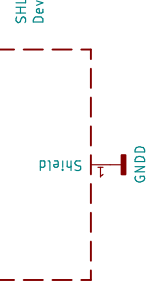
- FID1 Front Fiducial
FID3 Front Fiducial
FID4 Back Fiducial
FID5 Back Fiducial
FID6 Back Fiducial

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Blue dashes indicate traces that ought to be guarded using similar voltage guard ring. Remove solder mask from the guard rings to guard against leakage and contamination. Guard rings are added to vias in the input net on the other side of the board as well.



Stock shield symbol below slightly incorrect: it is the top that connects to GND while the bottom is not used



When used as designed (body soldered to the shield and removed), the height of this shield is 10mm and not hermetically sealed.

Instead, hermetic sealing is suggested to provide you with the ultimate in long term sensitivity stability in scientific applications. This is achieved by which will also benefit from J1 being a triax connector instead of the phone connector shown.

Hermetic sealing is achieved by:

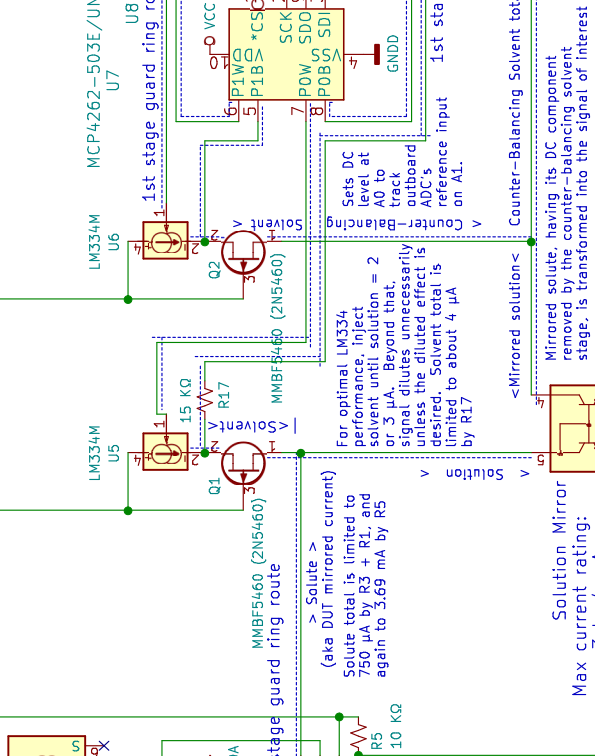
- #1) Solder sealing all micro-vias of the PCB under the shield, and
- #2) not using the shield body as a triax connector. Instead, use a triax connector and thoroughly soldering the triax connector to the shield. This will ensure the triax connector is dried desiccant package (supplied by manufacturer with U4) stuffed inside to minimize moisture degradation. U4 performance slightly over time in humid environments.

NOTE: Vcc net will remain labeled +5V until +3.3V operation is fully validated. Operation currently at +3.3V is a little sticky, likely due to the following note.

NOTE FOR 3.3V OPERATION — In 3.3V operation, the voltage drop that Q2 adds for the sake of not allowing the current to flow through the diode is not that is found to be the case, that JFET may be shorted across D to S with the expected result to be reduced signal formation.

MMBF5460 (2N5460) NOTE: SMD Source & Drain MUST BE interchangeable due to starting off this project with a SMD package. Since the manufacturer should not be prohibited by C, the manufacturer states that specific interchangeability is present in the MMBF5460 SMD package anyway. Also note: Q1 contributes nothing to functionality for both U7 and U8 since they are co-located, distant from other guard traces, and their guard trace weaves between board sides leaving no room for another.

2nd stage guard ring source



NOTE — These resistors are valued for 5V operation to set the reference input of the HX711 for highest gain. Future research is yet to be done for 3.3V operation. While the HX711 is not expected to be different, based simply on the reasoning that this reference voltage is about half of 3.3V already. LMC662 is rated for 5VDC minimum. 3.3VDC part yet to be spec'd.

NOTE THE ABOVE UNUSUAL USE OF, AND DISTINCTION BETWEEN CHEMISTRY TERMS "SOLUTE", "SOLVENT", AND "SOLUTION" ANALOGOUSLY APPLIED TO ELECTRICAL CURRENT

Q1,2 pinch-off testing: Q1,2 need to place enough voltage across LM334 at 68K [256 setting in 50K device] to 13K [66 setting in 50K device] while at the same time Q2 presents very high impedance load to U4C pin 4 as found by proving Q2 has not saturated.

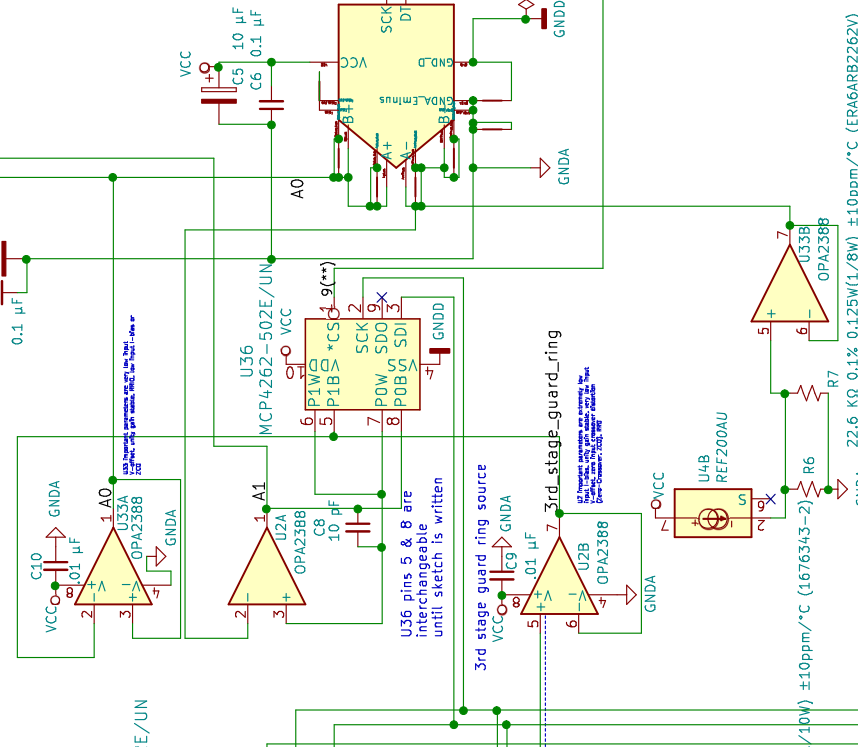
NOTE — Due to this current mirror being referenced low, the signal gets inverted (higher current=lower voltage). No stage following is also inverting, so unfortunately it becomes mirrored. I haven't done that to the point of being essential to the lay operator — not worth my time right now, all things considered. For now, the operator may just have to envision the plot line as equating to DUT stress or electrical resistance instead of conductance.

NOTE — Future temperature compensation is expected to be accomplished by examining and balancing the tempo of the temperature drift. If a different tempo is found to be required for ADC1 balance, changing the tempos of these resistors would be the solution.

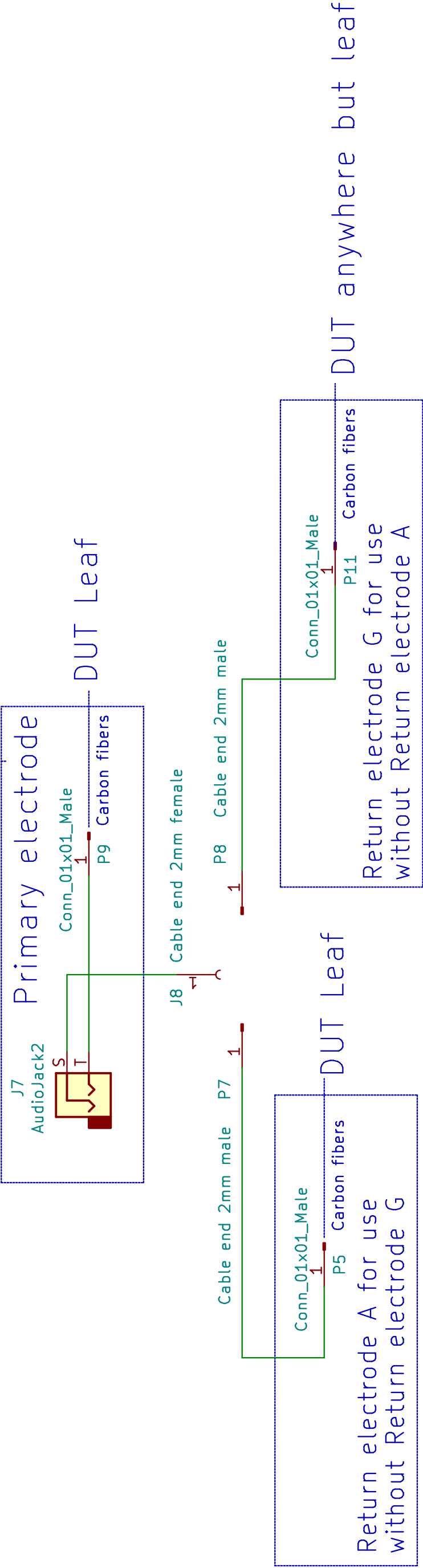
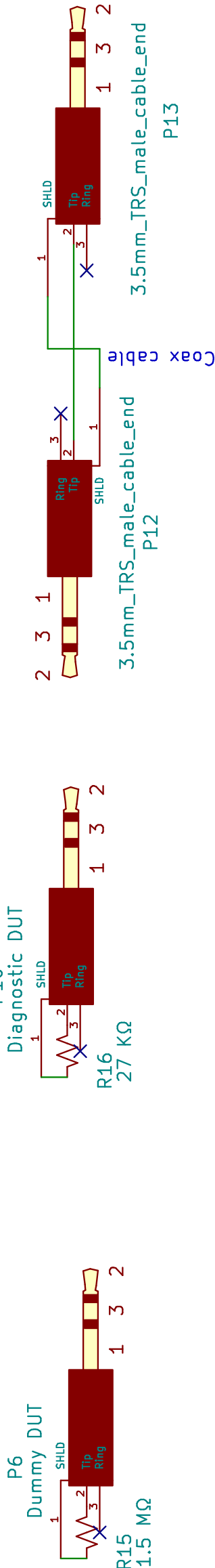
Only a single jumper to be used at a time. The jumper is used to select the modules and a third for ESP-01 adapter, though only one of the modules can be chosen from that lineup. If ESP-01 is needed to be used, the JPA shunt but also solder-jumper on board front to surrounding copper. If it is needed for connect to Rx, JPA jumpering is available connects to Rx of the other & vice versa. That is why you'll notice Tx printed on the wireless module goes to MCU Rx.

Conn_01x09_Female

Notes: U33, U34, and U35 need not be OPA320. It is shown this way for simplicity of BOM.



NOTE: These symbols are required to generate an accurate BOM. To use them in that way, copy them and paste them anywhere into the main page. They do not have to show within any sheet boundary. Generate the new BOM and delete the symbol copies from the main page, and main page only, when finished, always leaving the original symbols in this sheet. If the copies are left in the main page when later updating the PCB, they will interfere with the generation of the PCB Gerber files because these have no residencies on the PCB.



The pins inside the electrodes are to enable gold compatible finish electrical contact in the electrode assemblies for the carbon fiber. One pin belongs in each electrode assembly.

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